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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HZB6.8MWA

Silicon Planar Zener Diode for Surge Absorb



ADE-208-971A (Z)

Rev.1
Nov. 2001

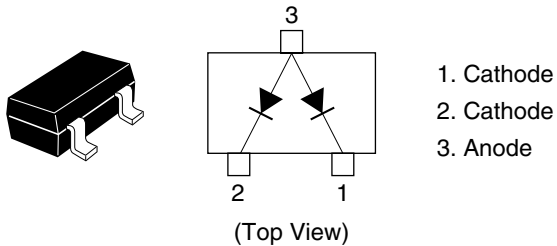
Features

- HZB6.8MWA has two devices in a monolithic, and can absorb surge.
- CMPAK package is suitable for high density surface mounting.

Ordering Information

Type No.	Laser Mark	Package Code
HZB6.8MWA	68M	CMPAK

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: Two device total, See Fig.2.

Electrical Characteristics *¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _z	6.47	—	7.00	V	I _z = 5 mA, 40 ms pulse
Reverse current	I _R	—	—	2	μA	V _R = 3.5 V
Capacitance	C	—	—	130	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	—	—	30	Ω	I _z = 5 mA
ESD-Capability * ² , * ³	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes: 1. Per one device.

2. Failure criterion ; I_R > 2 μA at V_R = 3.5 V.

3. Between cathode and anode

Main Characteristic

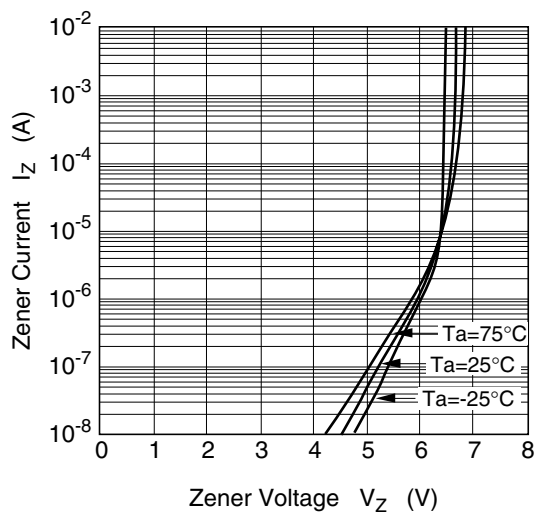


Fig.1 Zener current vs. Zener voltage

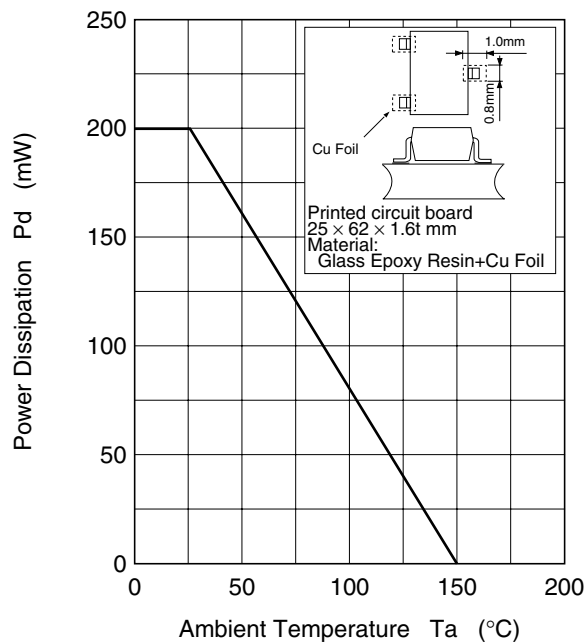
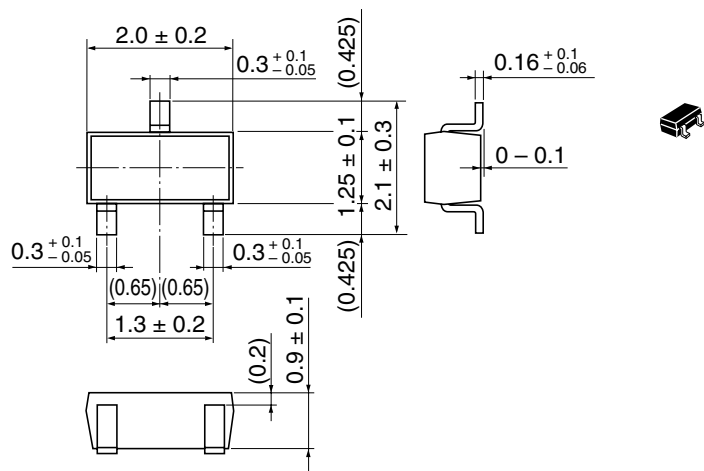


Fig.2 Power Dissipation vs. Ambient Temperature

Package Dimensions

As of July, 2001
 Unit: mm



Hitachi Code	CMPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.006 g

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